

N-channel 800 V, 2.8 Ω typ., 2.5 A MDmesh™ K5
Power MOSFETs in DPAK, TO-220FP, TO-220 and IPAK

Datasheet - production data

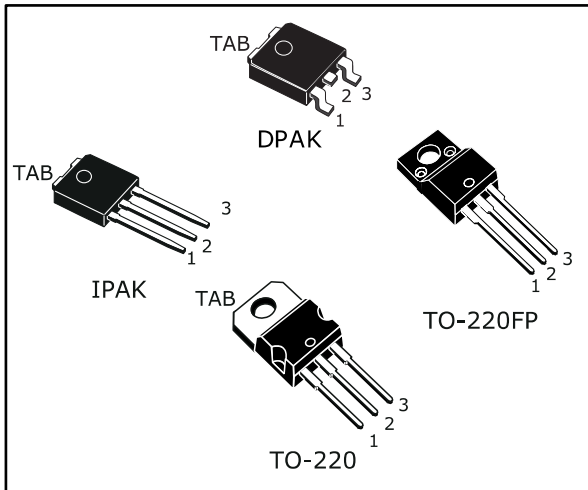
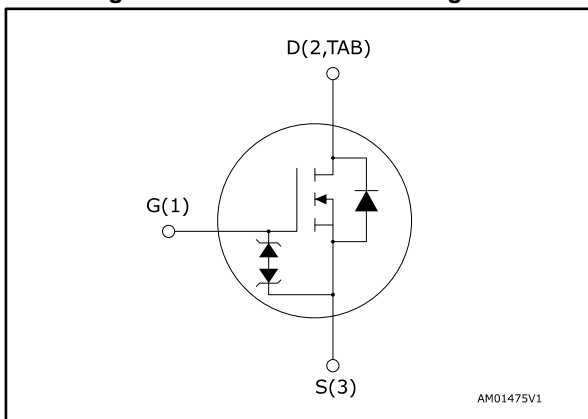


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STD3N80K5	800 V	3.5 Ω	2.5 A	60 W
STF3N80K5				20 W
STP3N80K5				60 W
STU3N80K5				

- Industry's lowest R_{DS(on)} x area
- Industry's best FoM (figure of merit)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

These very high voltage N-channel Power MOSFETs are designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1: Device summary

Order code	Marking	Package	Packing
STD3N80K5	3N80K5	DPAK	Tape and reel
STF3N80K5		TO-220FP	
STP3N80K5		TO-220	Tube
STU3N80K5		IPAK	

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuits	9
4	Package information	10
	4.1 DPAK (TO-252) type A package information.....	10
	4.2 DPAK (TO-252) type E package information.....	13
	4.3 DPAK (TO-252) packing information.....	15
	4.4 TO-220FP package information	17
	4.5 TO-220 type A package information.....	19
	4.6 IPAK (TO-251) type A package information	21
5	Revision history	23



1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value				Unit
		DPAK	TO-220FP	TO-220	IPAK	
V_{GS}	Gate-source voltage	±30				V
I_D	Drain current (continuous) at $T_C = 25\text{ °C}$	2.5				A
I_D	Drain current (continuous) at $T_C = 100\text{ °C}$	1.6				A
$I_D^{(1)}$	Drain current (pulsed)	10				A
P_{TOT}	Total dissipation at $T_C = 25\text{ °C}$	60	20	60	60	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat-sink ($t = 1\text{ s}$, $T_C = 25\text{ °C}$)		2.5			kV
$dv/dt^{(2)}$	Peak diode recovery voltage slope	4.5				V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50				
T_j	Operating junction temperature range	-55 to 150				°C
T_{stg}	Storage temperature range					

Notes:

- (1)Pulse width limited by safe operating area.
- (2) $I_{SD} \leq 2.5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$; $V_{DS\text{ peak}} < V_{(BR)DSS}$.
- (3) $V_{DS} \leq 640\text{ V}$.

Table 3: Thermal data

Symbol	Parameter	Value				Unit
		DPAK	TO-220FP	TO-220	IPAK	
$R_{thj-case}$	Thermal resistance junction-case	2.08	6.25	2.08		°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient		62.5	62.5	100	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50				°C/W

Notes:

- (1)When mounted on FR-4 board of 1 inch², 2 oz Cu.

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	1	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25\text{ °C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	65	mJ

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified

Table 5: On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	800			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 800\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 800\text{ V}$, $T_C = 125\text{ °C}^{(1)}$			50	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 10	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DD} = V_{GS}$, $I_D = 100\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 1\text{ A}$		2.8	3.5	Ω

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	130	-	pF
C_{oss}	Output capacitance		-	14	-	pF
C_{rss}	Reverse transfer capacitance		-	0.6	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ to }640\text{ V}$	-	20	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	9	-	pF
R_g	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	15.5	-	Ω
Q_g	Total gate charge	$V_{DD} = 640\text{ V}$, $I_D = 2.5\text{ A}$ $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 19: "Test circuit for gate charge behavior")	-	9.5	-	nC
Q_{gs}	Gate-source charge		-	1.5	-	nC
Q_{gd}	Gate-drain charge		-	7.5	-	nC

Notes:

⁽¹⁾ $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

⁽²⁾ $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400\text{ V}$, $I_D = 1.25\text{ A}$, $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (see Figure 18: "Test circuit for resistive load switching times" and Figure 23: "Switching time waveform")	-	8.5	-	ns
t_r	Rise time		-	10.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	20.5	-	ns
t_f	Fall time		-	25	-	ns

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		2.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		10	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 2.5\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 2.5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 20: "Test circuit for inductive load switching and diode recovery times")	-	265		ns
Q_{rr}	Reverse recovery charge		-	1.2		μC
I_{RRM}	Reverse recovery current		-	9.2		A
t_{rr}	Reverse recovery time	$I_{SD} = 2.5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 20: "Test circuit for inductive load switching and diode recovery times")	-	430		ns
Q_{rr}	Reverse recovery charge		-	1.9		μC
I_{RRM}	Reverse recovery current		-	8.8		A

Notes:

(1)Pulse width limited by safe operating area

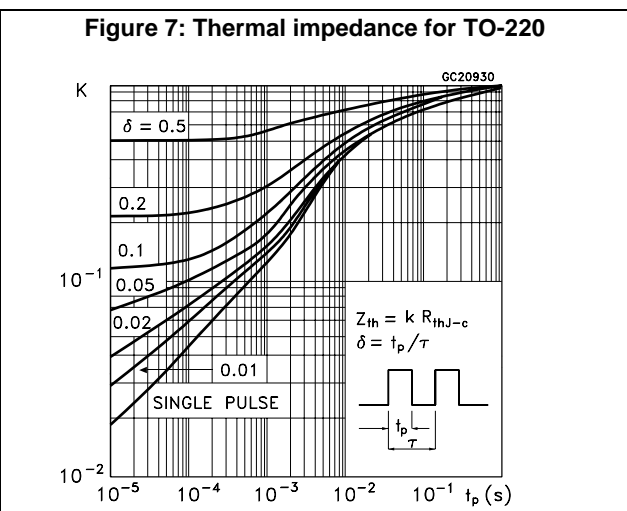
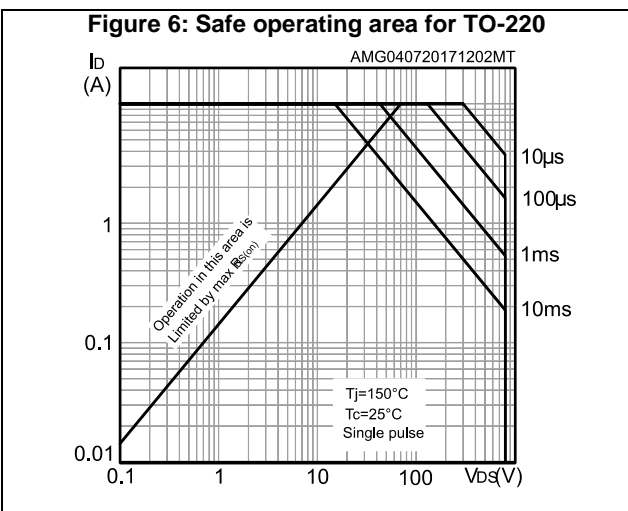
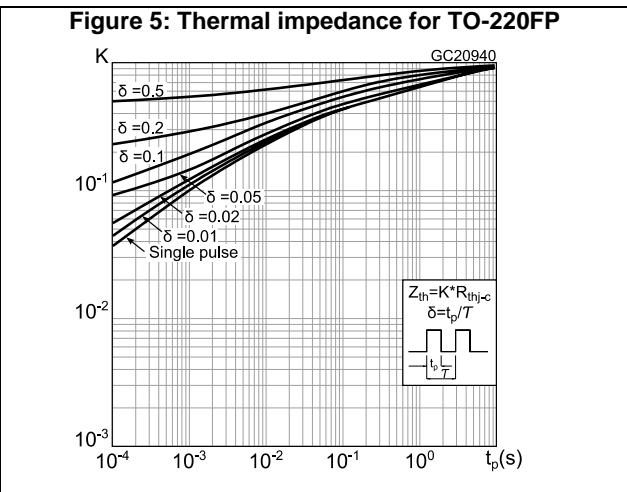
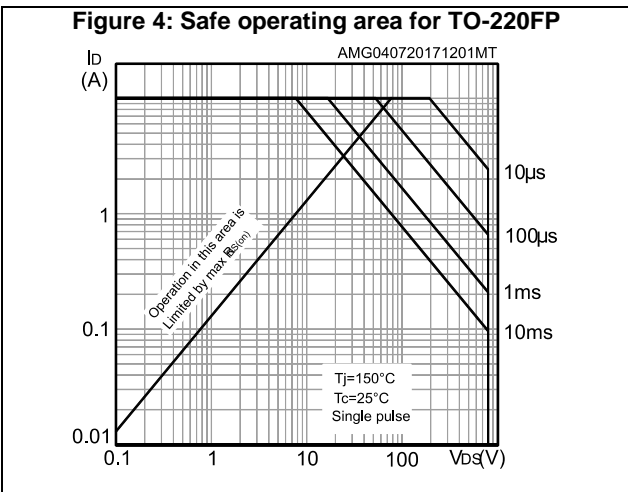
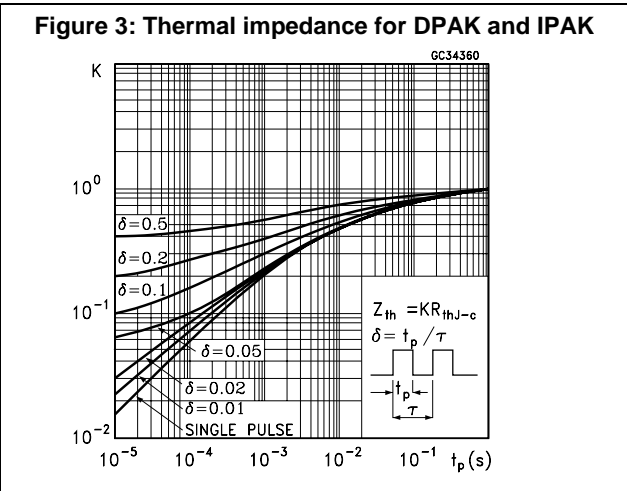
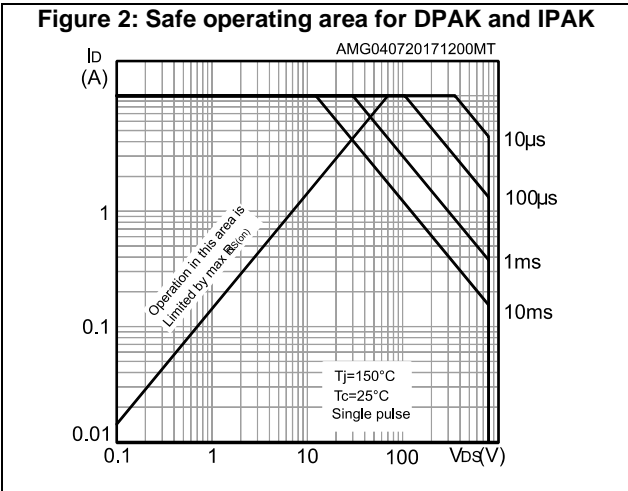
(2)Pulsed: pulse duration = 300 μs , duty cycle 1.5%

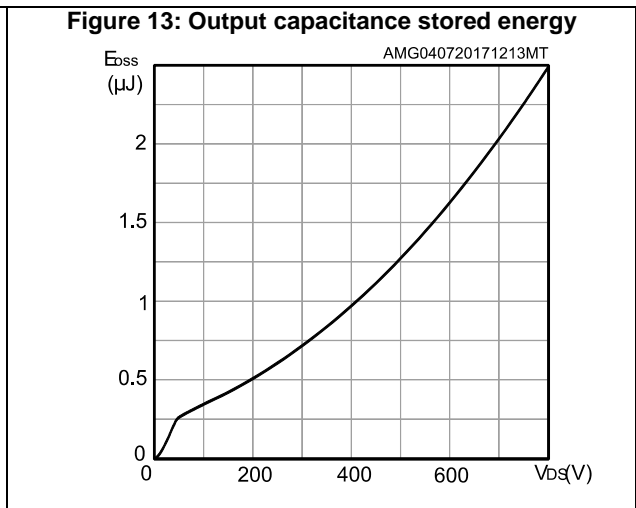
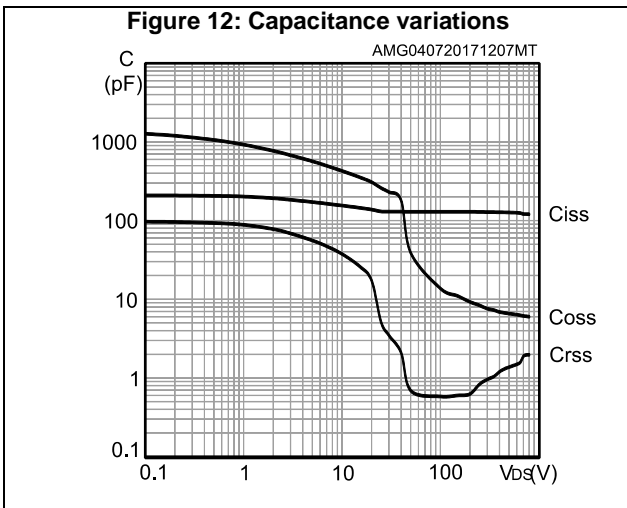
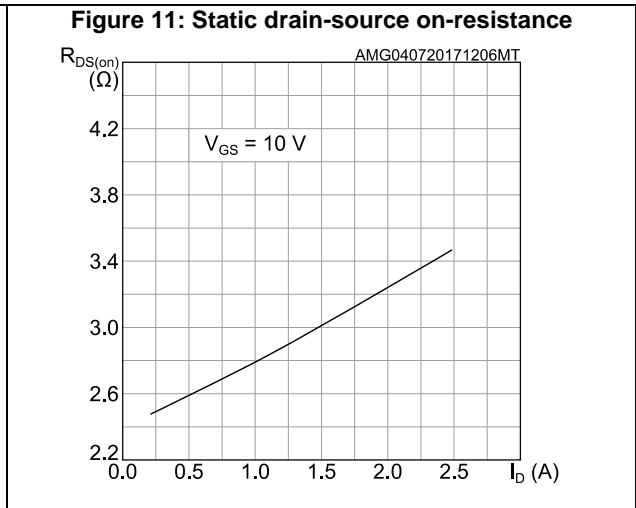
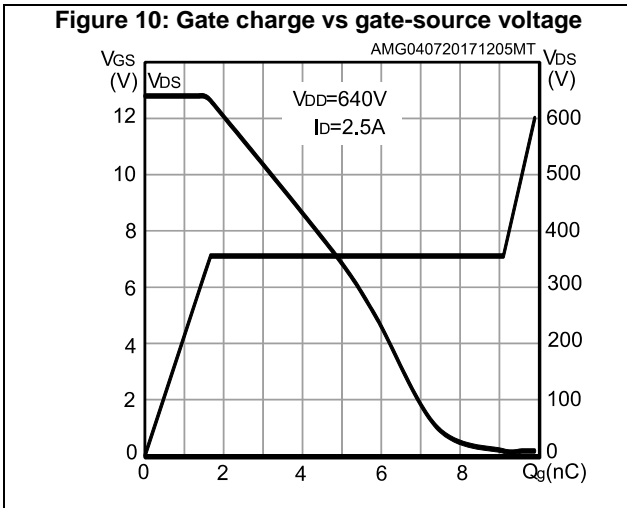
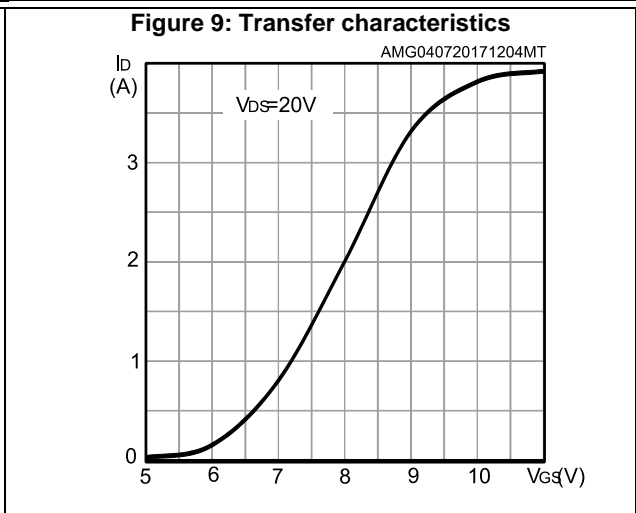
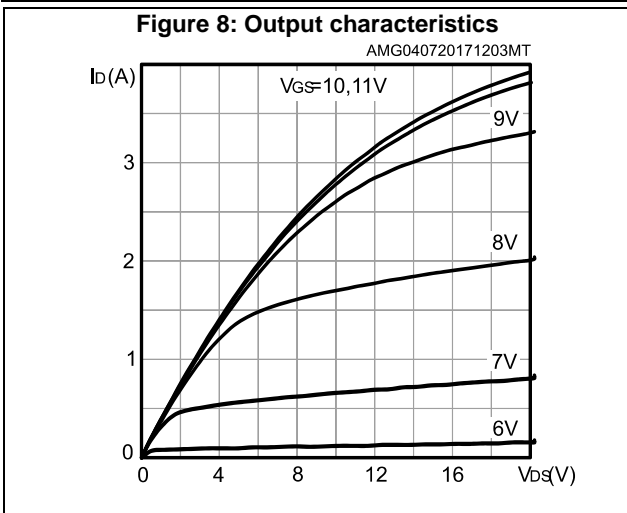
Table 9: Gate-source Zener diode

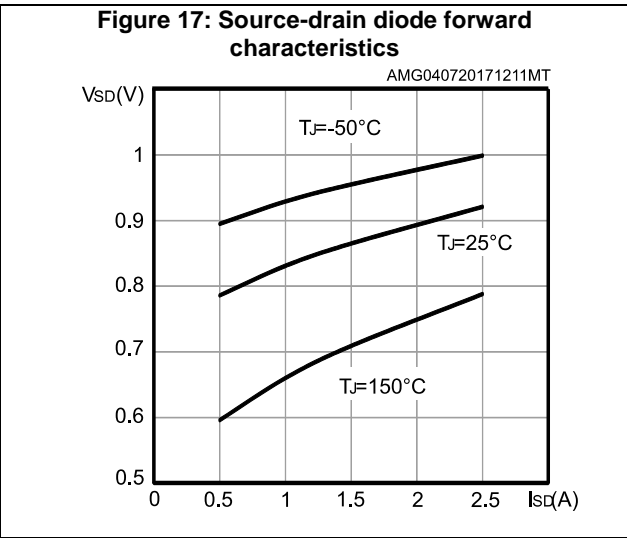
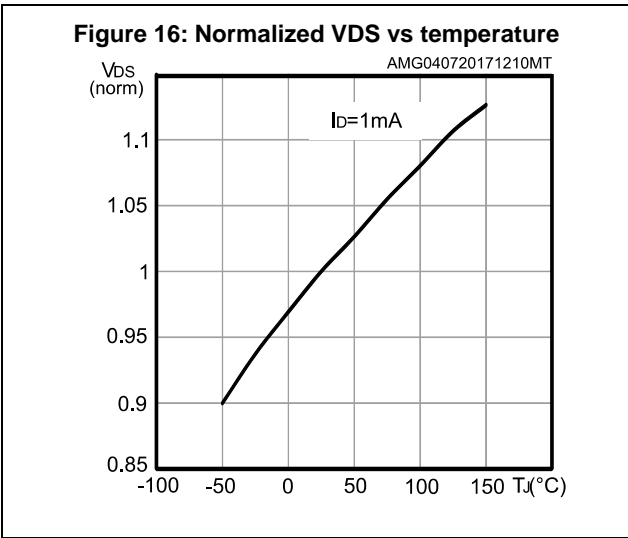
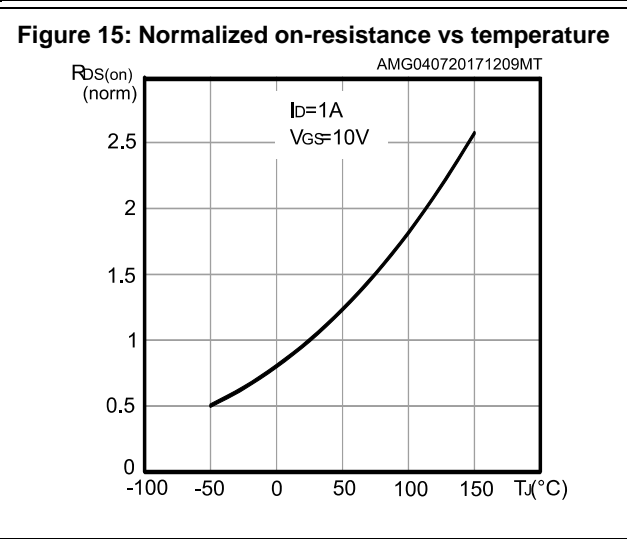
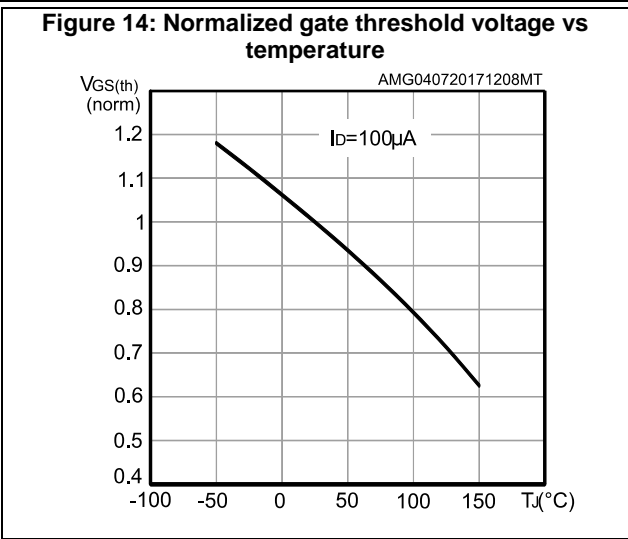
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1\text{ mA}$, $I_D = 0\text{ A}$	± 30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

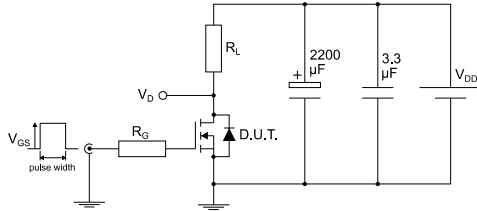






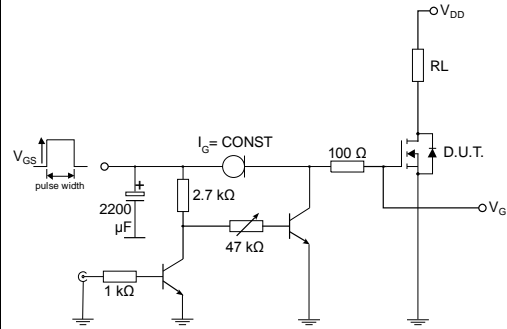
3 Test circuits

Figure 18: Test circuit for resistive load switching times



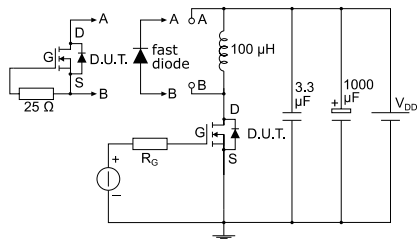
AM01468v1

Figure 19: Test circuit for gate charge behavior



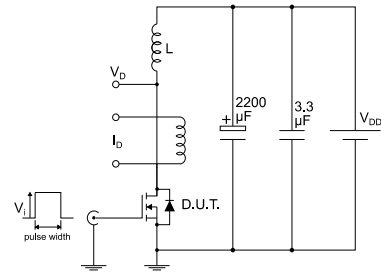
AM01469v10

Figure 20: Test circuit for inductive load switching and diode recovery times



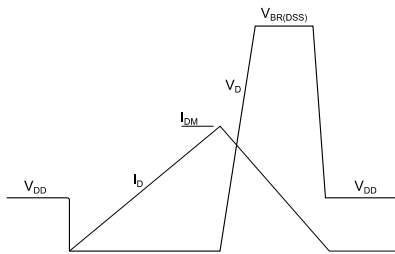
AM01470v1

Figure 21: Unclamped inductive load test circuit



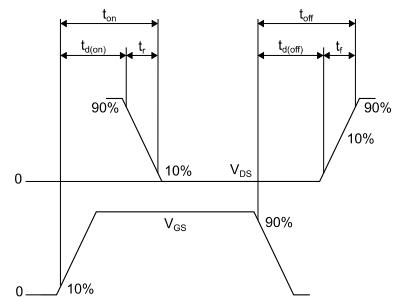
AM01471v1

Figure 22: Unclamped inductive waveform



AM01472v1

Figure 23: Switching time waveform



AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A package information

Figure 24: DPAK (TO-252) type A package outline

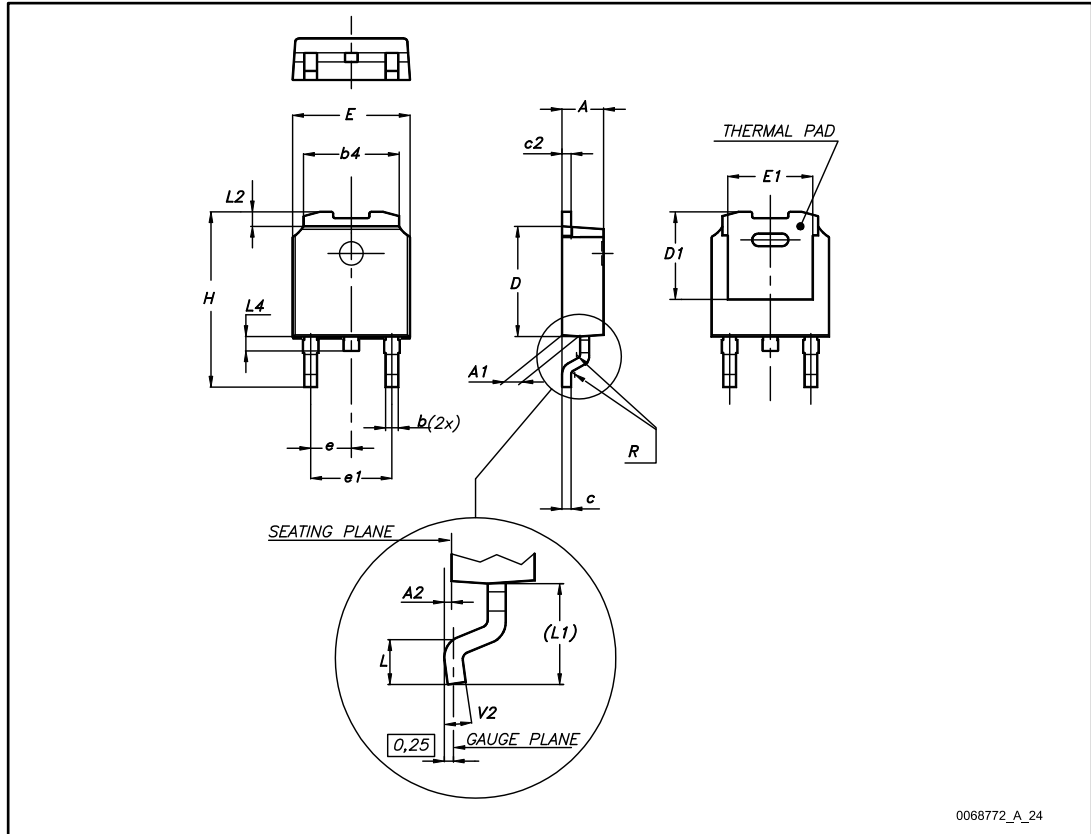
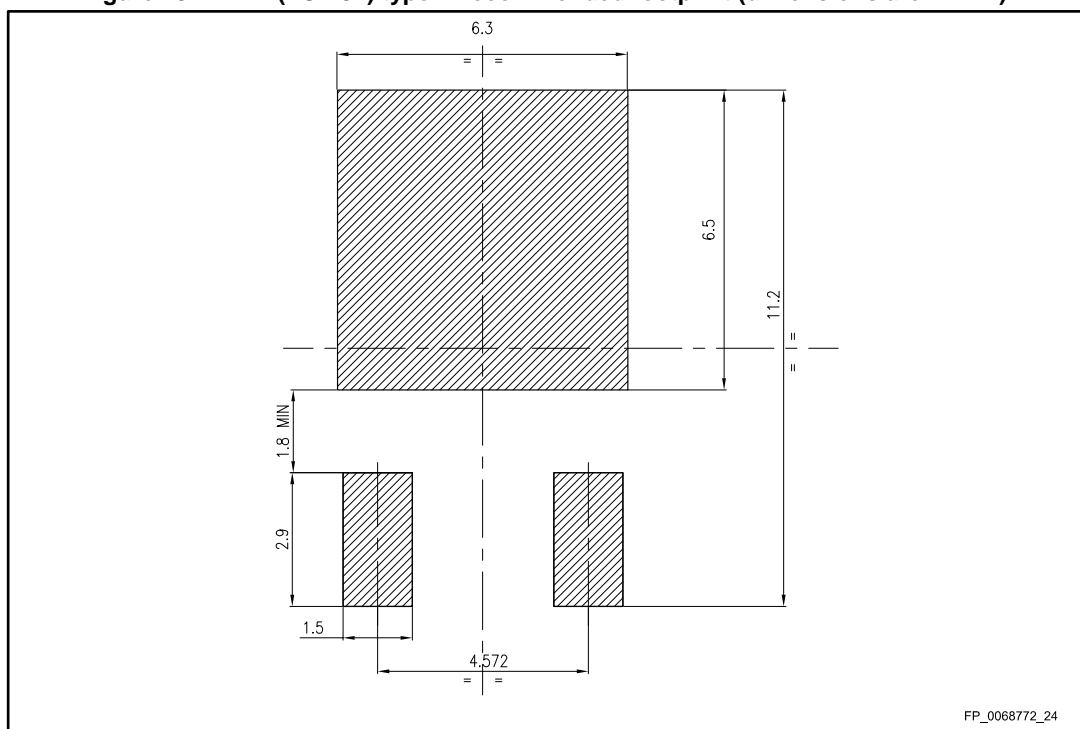


Table 10: DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 25: DPAK (TO-252) type A recommended footprint (dimensions are in mm)



4.2 DPAK (TO-252) type E package information

Figure 26: DPAK (TO-252) type E package outline

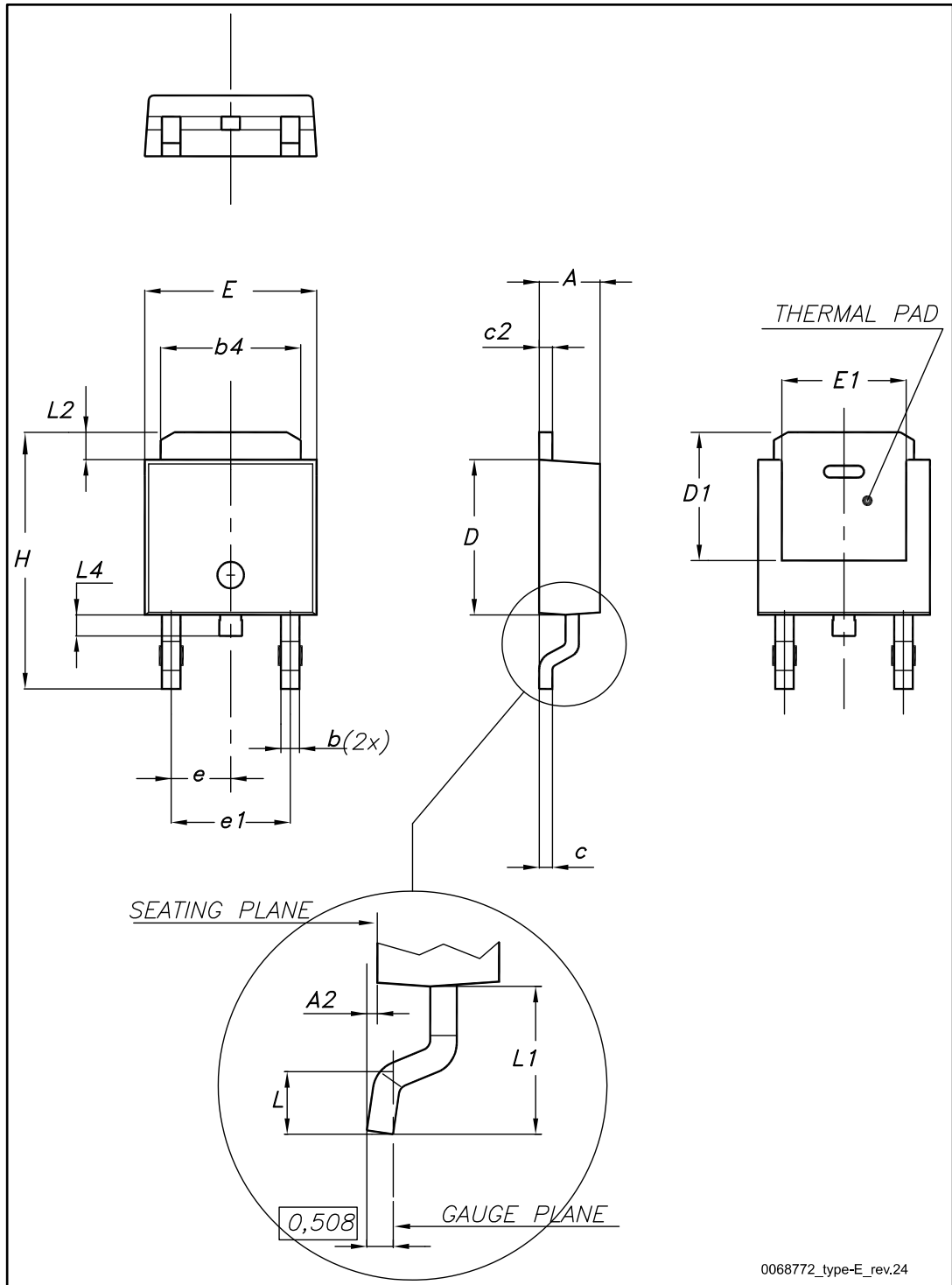
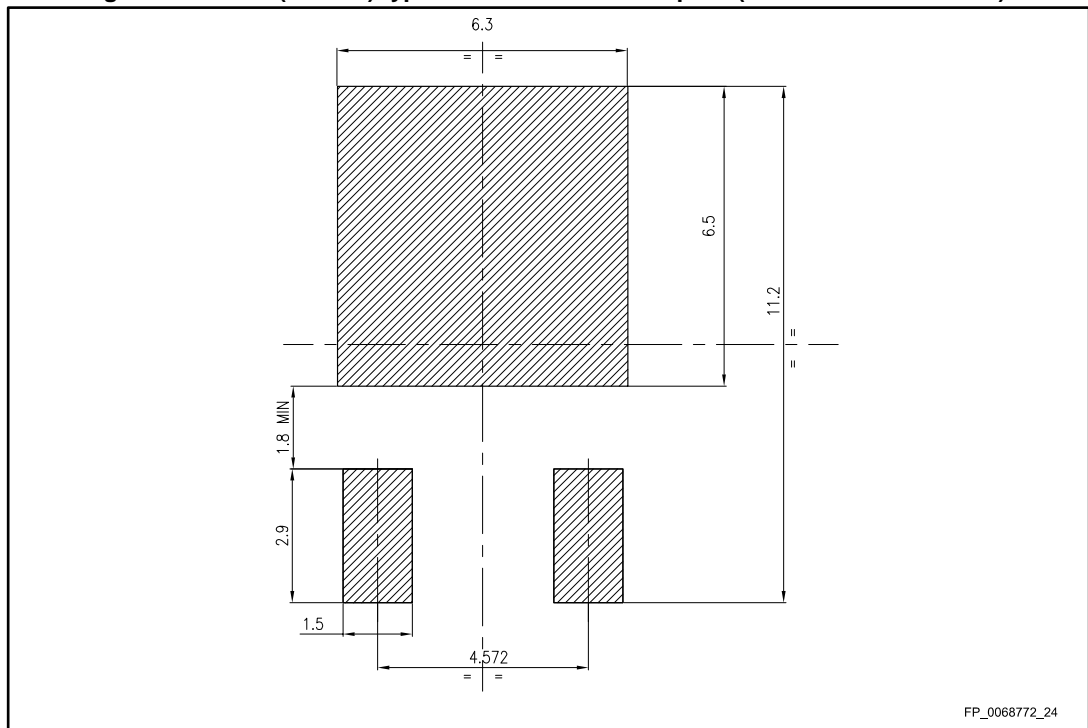


Table 11: DPAK (TO-252) type E mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.18		2.39
A2			0.13
b	0.65		0.884
b4	4.95		5.46
c	0.46		0.61
c2	0.46		0.60
D	5.97		6.22
D1	5.21		
E	6.35		6.73
E1	4.32		
e		2.286	
e1		4.572	
H	9.94		10.34
L	1.50		1.78
L1		2.74	
L2	0.89		1.27
L4			1.02

Figure 27: DPAK (TO-252) type E recommended footprint (dimensions are in mm)



FP_0068772_24

4.3 DPAK (TO-252) packing information

Figure 28: DPAK (TO-252) tape outline

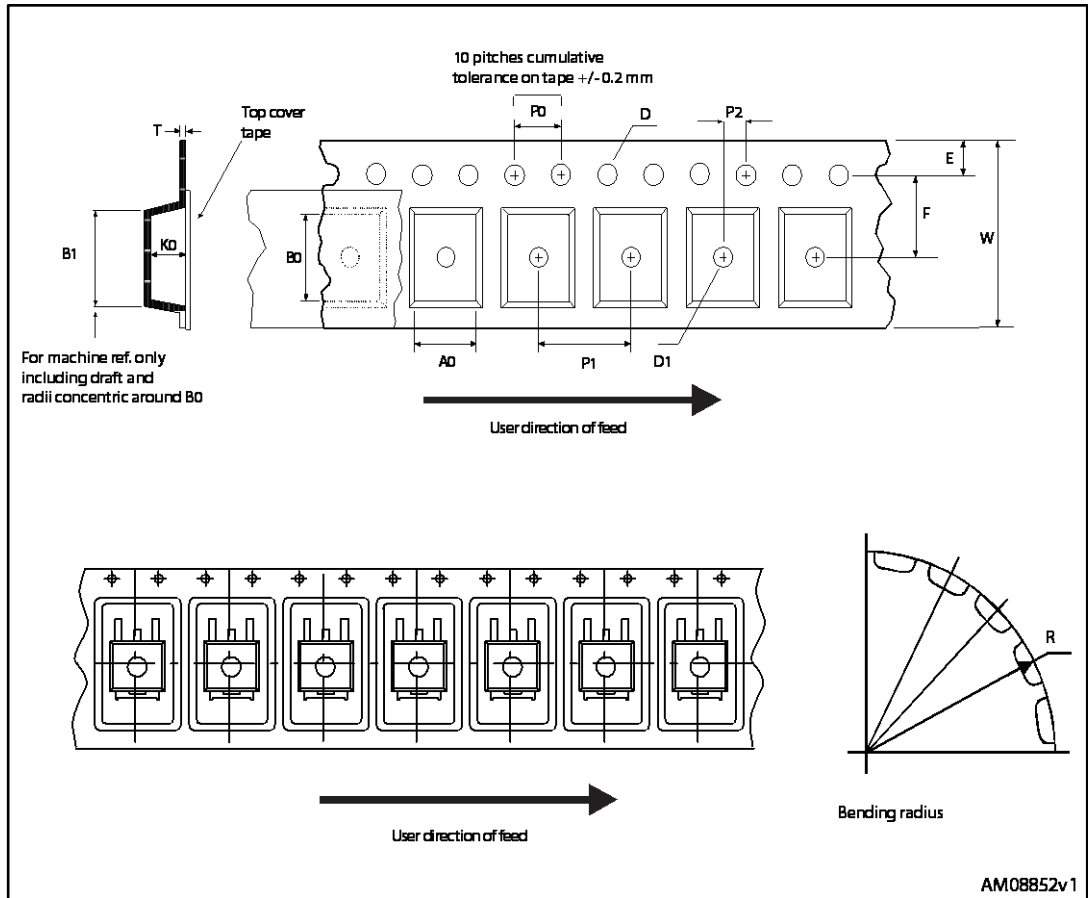
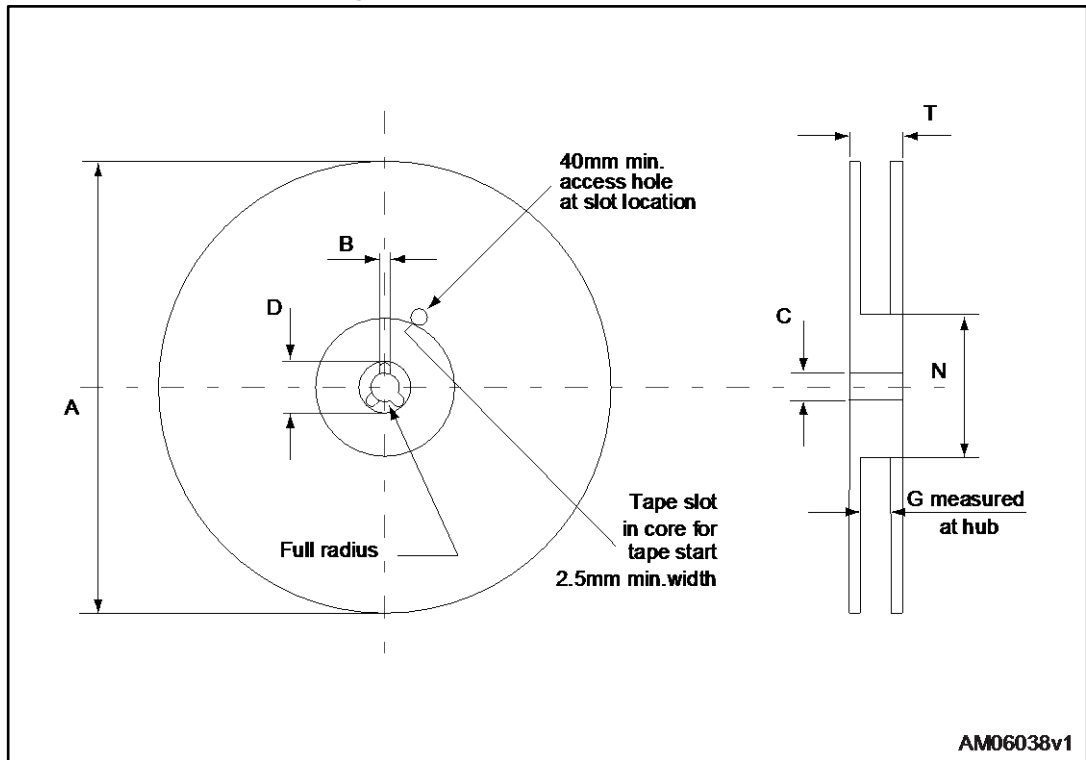


Figure 29: DPAK (TO-252) reel outline



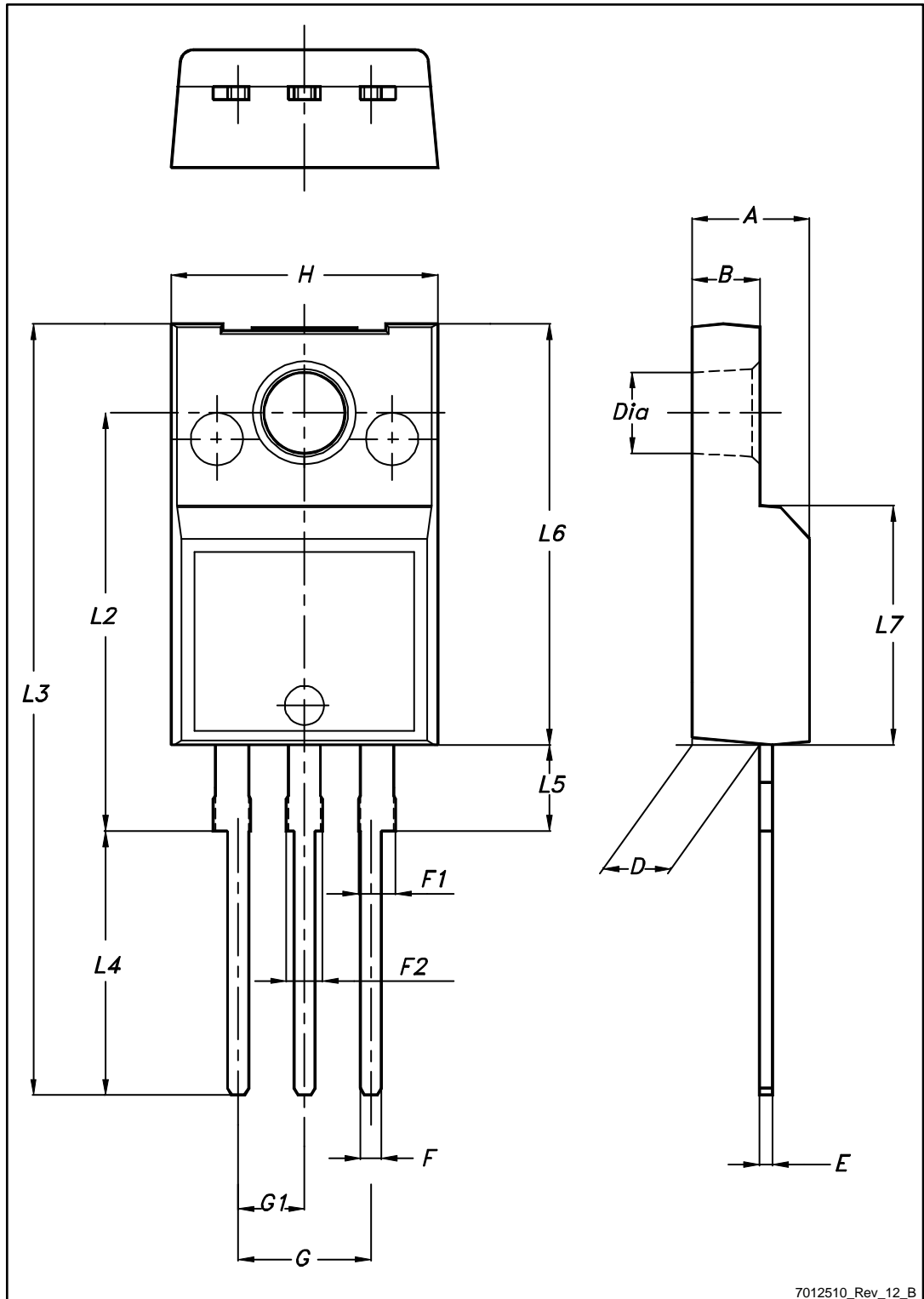
AM06038v1

Table 12: DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

4.4 TO-220FP package information

Figure 30: TO-220FP package outline



7012510_Rev_12_B

Table 13: TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

4.5 TO-220 type A package information

Figure 31: TO-220 type A package outline

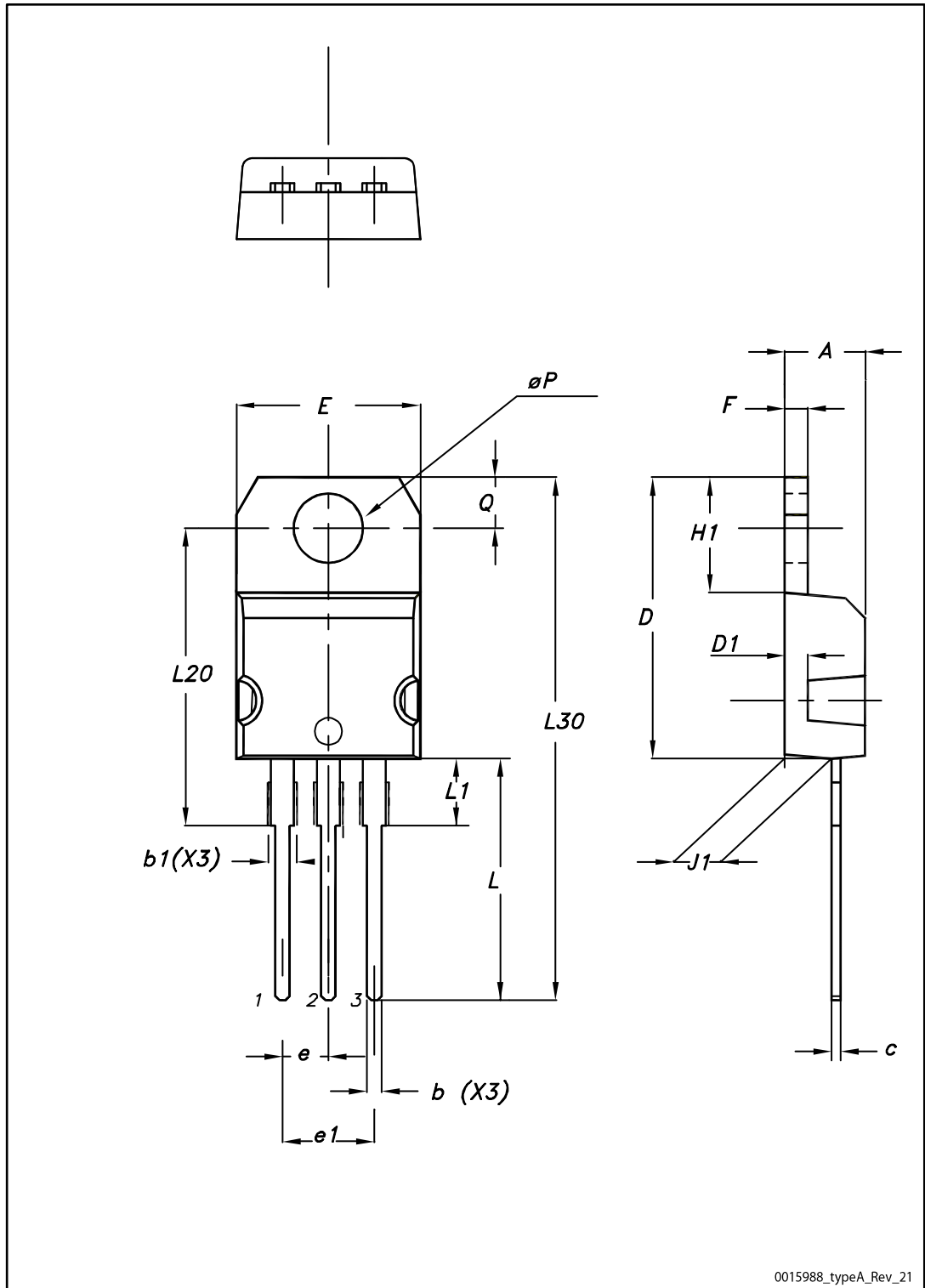


Table 14: TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

4.6 IPAK (TO-251) type A package information

Figure 32: IPAK (TO-251) type A package outline

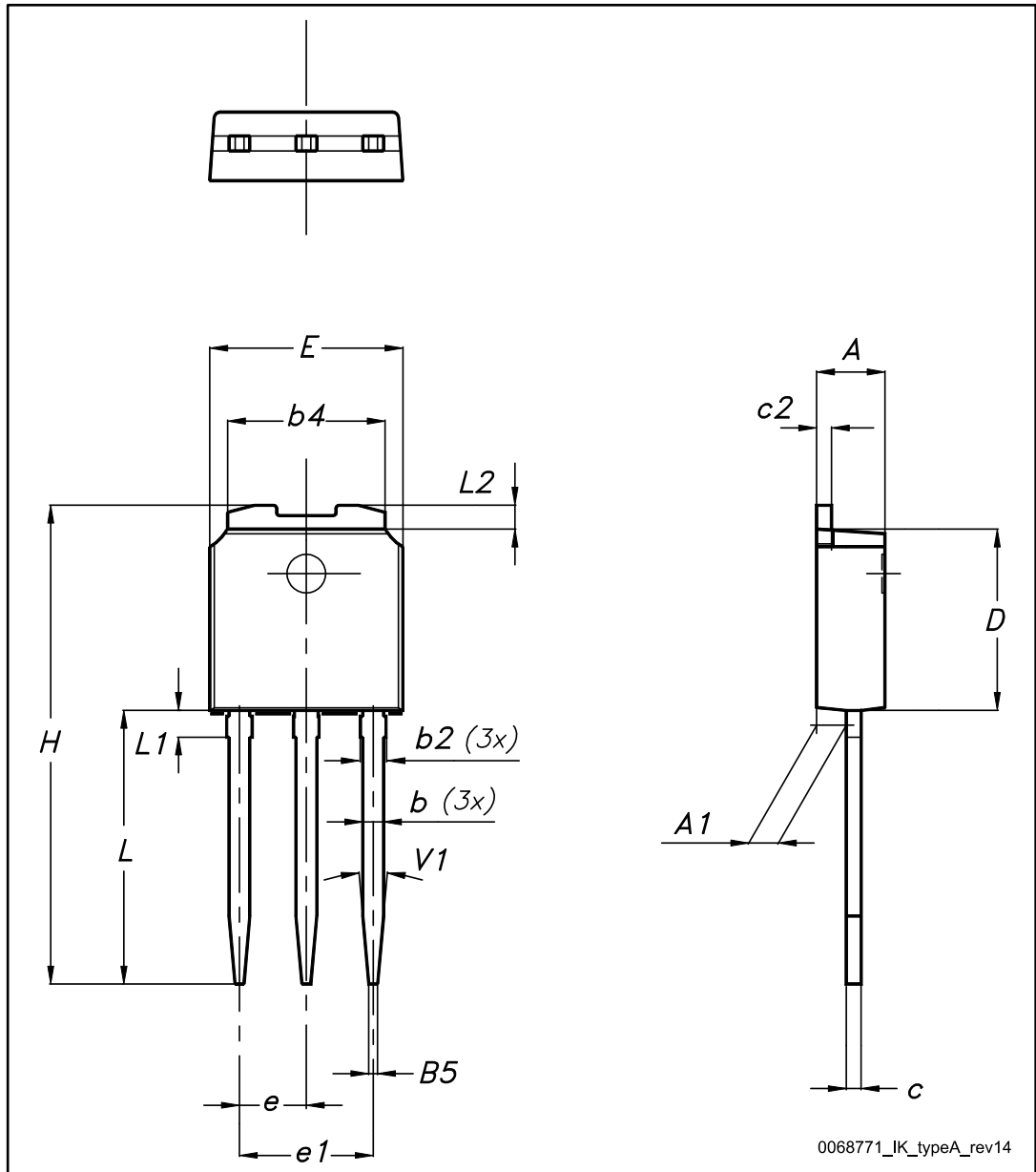


Table 15: IPAK (TO-251) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

5 Revision history

Table 16: Document revision history

Date	Revision	Changes
12-Jul-2013	1	First release.
15-Jan-2014	2	<ul style="list-style-type: none"> – Modified: PTOT and EAS values in Table 2 – Modified: Rthj-case values in Table 3 – Modified: the entire typical values in Table 5 and 6 – Modified: ISD and ISDM max values and typical values in Table 7 – Updated: Table 24 and Table 9 – Added: Section 2.1: Electrical characteristics (curves) – Minor text changes
17-Jan-2014	3	<ul style="list-style-type: none"> – Modified: Figure 8 and 9 – Minor text changes
17-Jul-2017	4	Updated Table 7: "Switching times" and Section 4: "Package information" . Minor text changes.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2017 STMicroelectronics – All rights reserved

单击下面可查看定价，库存，交付和生命周期等信息

[>>STMicro\(意法半导体\)](#)